TOSHIBA

TOSHIBA Field Effect Transistor Silicon P Channel MOS Type (U-MOS IV)

TPCF8303

Notebook PC Applications Portable Equipment Applications

• Low drain-source ON resistance: RDS (ON) = $58 \text{ m}\Omega$ (typ.)

• High forward transfer admittance: $|Y_{fs}| = 6.0 \text{ S (typ.)}$

• Low leakage current: $IDSS = -10 \mu A (max) (VDS = -20 V)$

• Enhancement-model: $V_{th} = -0.45$ to -1.2 V

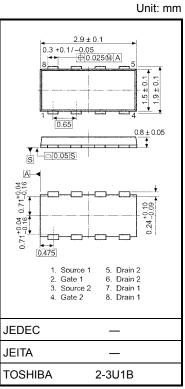
 $(V_{DS} = -10 \text{ V}, I_{D} = -200 \text{ }\mu\text{A})$

Maximum Ratings (Ta = 25°C)

Cha	Symbol	Rating	Unit		
Drain-source volta	ge	V_{DSS}	-20	V	
Drain-gate voltage	Drain-gate voltage (R _{GS} = 20 k Ω)			V	
Gate-source voltage	Gate-source voltage			V	
Drain current	DC (Note 1)	ΙD	-3.0	Α	
Diam current	Pulse (Note 1)	I_{DP}	-20 -20 ±8	ζ	
Drain power dissipation (t = 5 s) (Note 2a)	Single-device operation (Note 3a)	P _{D (1)}	1.35	W	
	Single-device value at dual operation (Note 3b)	P _{D (2)}	1.12		
Drain power dissipation (t = 5 s) (Note 2b)	Single-device operation (Note 3a)	P _{D (1)}	0.53		
	Single-device value at dual operation (Note 3b)	P _{D (2)}	0.33		
Single pulse avala	nche energy (Note 4)	E _{AS}	0.58	mJ	
Avalanche current		I _{AR}	-1.5	Α	
Repetitive avalanc Single-device value	E _{AR}	0.11	mJ		
Channel temperatu	ıre	T _{ch}	150	°C	
Storage temperatu	re range	T _{stg}	-55~150	°C	

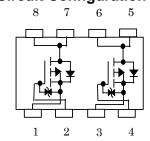
Note: For (Note 1), (Note 2), (Note 3), (Note 4), (Note 5) and (Note 6), please refer to the next page.

This transistor is an electrostatic sensitive device. Please handle with caution.

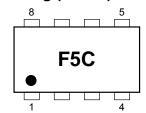


Weight: 0.011 g (typ.)

Circuit Configuration



Marking (Note 6)

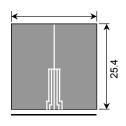


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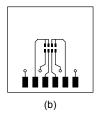
Thermal Characteristics

Characteristics		Symbol	Max	Unit	
Thermal resistance, channel to ambient (t = 5 s) (Note 2a)	Single-device operation (Note 3a)	R _{th (ch-a) (1)}	92.6	°C/W	
	Single-device value at dual operation (Note 3b)	R _{th (ch-a) (2)}	111.6		
Thermal resistance, channel to ambient (t = 5 s) (Note 2b)	Single-device operation (Note 3a)	R _{th (ch-a) (1)}	235.8	°C/W	
	Single-device value at dual operation (Note 3b)	R _{th (ch-a) (2)}	378.8	C/VV	

- Note 1: Please use devices on condition that the channel temperature is below 150°C.
- Note 2: (a) Device mounted on a glass-epoxy board (b) Device mounted on a glass-epoxy board (b)



FR-4 25.4 × 25.4 × 0.8 (Unit: mm)



FR-4 $25.4\times25.4\times0.8$ (Unit: mm)

- Note 3: a) The power dissipation and thermal resistance values are shown for a single device (During single-device operation, power is only applied to one device.).
 - b) The power dissipation and thermal resistance values are shown for a single device (During dual operation, power is evenly applied to both devices.).
- Note 4: V_{DD} = -16 V, T_{ch} = 25°C (initial), L = 0.2 mH, R_G = 25 Ω , I_{AR} = -1.5 A
- Note 5: Repetitive rating; Pulse width limited by Max. Channel temperature.
- Note 6: Black round marking " "locates on the left lower side of parts number marking "F5C" indicates terminal No. 1.

Electrical Characteristics (Ta = 25°C)

Cha	aracteristics	Symbol	Test Condition	Min	Тур.	Max	Unit	
Gate leakage cur	rrent	I _{GSS}	$V_{GS} = \pm 8V, V_{DS} = 0 V$	_	_	±10	μΑ	
Drain cut-off curr	ent	I _{DSS}	V _{DS} = -20 V, V _{GS} = 0 V	_	_	-10	μΑ	
Drain-source bre	akdown voltage	V (BR) DSS	$I_D = -10 \text{ mA}, V_{GS} = 0 \text{ V}$	-20 — — -10 — —		_	V	
Diam-source bie	akdown voltage	V _{(BR) DSX}	$I_D = -10 \text{ mA}, V_{GS} = 8 \text{ V}$			V		
Gate threshold ve	oltage	V _{th}	$V_{DS} = -10 \text{ V}, I_D = -200 \mu A$	-0.45	_	-1.2	٧	
		R _{DS (ON)}	$V_{GS} = -1.8 \text{ V}, I_D = -1.5 \text{ A}$	_	120	250		
Drain-source ON	resistance	R _{DS (ON)}	$V_{GS} = -2.5 \text{ V}, I_D = -1.5 \text{ A}$	_	63	87	mΩ	
		R _{DS} (ON)	$V_{GS} = -4.5 \text{ V}, I_D = -1.5 \text{ A}$	_	43	58		
Forward transfer	er admittance $ Y_{fs} $ $V_{DS} = -10 \text{ V}, I_D = -1.5 \text{ A}$		$V_{DS} = -10 \text{ V}, I_D = -1.5 \text{ A}$	3.0	6.0	_	S	
Input capacitance		C _{iss}		_	860	_		
Reverse transfer	capacitance	C _{rss}	$V_{DS} = -10 \text{ V}, V_{GS} = 0 \text{ V}, f = 1 \text{ MHz}$	_	110	_	pF	
Output capacitance		C _{oss}		_	140	_		
	Rise time	t _r	V _{GS} -5 V	_	5.6	_		
Cuitabina tima	Turn-on time	t _{on}		_	16	_		
Switching time	Fall time	t _f		_	16	_	ns	
	Turn-off time	t _{off}	$V_{DD} \simeq -10 \text{ V}$ Duty $\leq 1\%$, $t_W = 10 \mu\text{s}$	_	55	_		
Total gate charge (gate-source plus		Qg	V _{DD} ≃ -16 V, V _{GS} = -5 V,	_ 11 _		_		
Gate-source charge1		Q _{gs1}	$I_D = -3 \text{ A}$	_	0.9	_	nC	
Gate-drain ("miller") charge		Q _{gd}		_	2.7	_		

Source-Drain Ratings and Characteristics (Ta = 25°C)

Characterist	ics	Symbol	Test Condition	Min	Тур.	Max	Unit
Drain reverse current	Pulse (Note 1)	I _{DRP}	_	_	_	-12	Α
Forward voltage (diode)		V_{DSF}	$I_{DR} = -3.0 \text{ A}, V_{GS} = 0 \text{ V}$	_	_	1.2	V

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